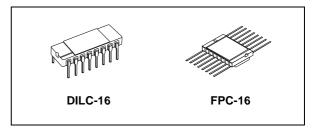


# RAD-HARD HEX BUFFER/CONVERTER

- HIGH SPEED: t (TVD)
  - $t_{PD} = 8ns (TYP.) at V_{CC} = 6V$
- LOW POWER DISSIPATION:
  I<sub>CC</sub> = 1μA(MAX.) at T<sub>A</sub>=25°C
- HIGH NOISE IMMUNITY: V = 28% V = 28% V = (MI
- V<sub>NIH</sub> = V<sub>NIL</sub> = 28% V<sub>CC</sub> (MIN.) ■ SYMMETRICAL OUTPUT IMPEDANCE:
- |I<sub>OH</sub>| = I<sub>OL</sub> = 6mA (MIN) ■ BALANCED PROPAGATION DELAYS: t<sub>PLH</sub> ≅ t<sub>PHL</sub>
- WIDE OPERATING VOLTAGE RANGE: V<sub>CC</sub> (OPR) = 2V to 6V
- PIN AND FUNCTION COMPATIBLE WITH 54 SERIES 4050
- SPACE GRADE-1: ESA SCC QUALIFIED
- 50 krad QUALIFIED, 100 krad AVAILABLE ON REQUEST
- NO SEL UNDER HIGH LET HEAVY IONS IRRADIATION
- DEVICE FULLY COMPLIANT WITH SCC-9401-038

#### DESCRIPTION

The M54HC4050 is an high speed CMOS HEX BUFFER fabricated with silicon gate  $\mbox{C}^2\mbox{MOS}$  technology.



#### **ORDER CODES**

PACKAGE	FM	EM
DILC	M54HC4050D	M54HC4050D1
FPC	M54HC4050K	M54HC4050K1

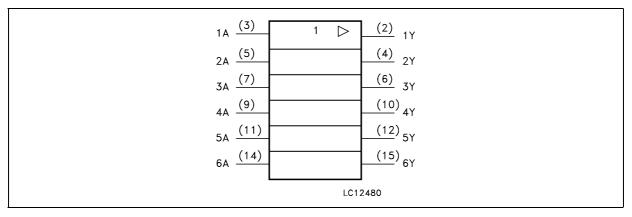
The internal circuit is composed of 3 stages, which enables high noise immunity and a stable output. Input protection circuits are different from those of the high speed CMOS IC's.

The  $V_{CC}$  side diodes are designed to allow logic-level conversion from high-level voltages (up to 13V) to low level voltages.

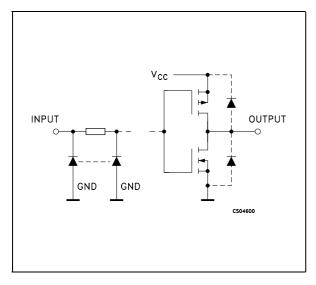
#### 116 NC $V_{cc}$ 1 [] 16 NC V<sub>cc</sub> 6Y 6Y 1Y 2 15 1Y 15 Д 1A 3 14 6A 6A 1A 14 2Y 4 [ 13 NC 2Y 13 NC 12 5Y 12 5Y 2A 5 2A $\bigtriangleup$ 5A 5A 3Y 3Y 6 11 11 $\wedge$ Δ 4Y 3A 7 10 4Y 3A 10 GND 4A GND 8 **[** 4A 8 9 9 CS19480 CS19490 Rev. 1 May 2004 1/9

#### **PIN CONNECTION**

#### Figure 1: IEC Logic Symbols



#### Figure 2: Input And Output Equivalent Circuit



# Table 1: Pin Description

PIN N°	SYMBOL	NAME AND FUNCTION			
2, 4, 6, 10, 12, 15	1Y to 6Y	Data Outputs			
3, 5, 7, 9, 11, 14	1A to 6A	Data Inputs			
13, 16	NC	Not Connected			
8	GND	Ground (0V)			
1	V <sub>CC</sub>	Positive Supply Voltage			

# Table 2: Truth Table

INPUT	OUTPUT
nA	nY
L	L
Н	Н

### **Table 3: Absolute Maximum Ratings**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply Voltage	-0.5 to +7	V
VI	DC Input Voltage	-0.5 to 15	V
Vo	DC Output Voltage	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	- 20	mA
I <sub>OK</sub>	DC Output Diode Current	± 20	mA
۱ <sub>۵</sub>	DC Output Current	± 25	mA
$I_{CC}$ or $I_{GND}$	DC V <sub>CC</sub> or Ground Current	± 50	mA
PD	Power Dissipation	300	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
ΤL	Lead Temperature (10 sec)	265	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied

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-	'	~

# Table 4: Recommended Operating Conditions

Symbol	Parameter	Value	Unit		
V <sub>CC</sub>	Supply Voltage		2 to 6	V	
VI	Input Voltage	0 to 13	V		
Vo	Output Voltage	utput Voltage			
T <sub>op</sub>	Operating Temperature		-55 to 125	°C	
	Input Rise and Fall Time	$V_{CC} = 2.0V$	0 to 1000	ns	
t <sub>r</sub> , t <sub>f</sub>		$V_{CC} = 4.5V$	0 to 500	ns	
		$V_{CC} = 6.0V$	0 to 400	ns	

# Table 5: DC Specifications

		٦	est Condition				Value				
Symbol	Parameter	v <sub>cc</sub>		т	A = 25°	С	-40 to	₀ 85°C	-55 to	125°C	Unit
		(V)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	l
V <sub>IH</sub>	High Level Input	2.0		1.5			1.5		1.5		
	Voltage	4.5		3.15			3.15		3.15		V
		6.0		4.2			4.2		4.2		
V <sub>IL</sub>	Low Level Input	2.0				0.5		0.5		0.5	l
	Voltage	4.5				1.35		1.35		1.35	V
		6.0				1.8		1.8		1.8	
V <sub>OH</sub>	High Level Output	2.0	I <sub>O</sub> =-20 μΑ	1.9	2.0		1.9		1.9		l
	Voltage	4.5	I <sub>O</sub> =-20 μA	4.4	4.5		4.4		4.4		l
		6.0	I <sub>O</sub> =-20 μA	5.9	6.0		5.9		5.9		V
		4.5	I <sub>O</sub> =-4.0 mA	4.18	4.31		4.13		4.10		l
		6.0	I <sub>O</sub> =-5.2 mA	5.68	5.8		5.63		5.60		l
V <sub>OL</sub>	Low Level Output	2.0	I <sub>O</sub> =20 μA		0.0	0.1		0.1		0.1	
	Voltage	4.5	I <sub>O</sub> =20 μA		0.0	0.1		0.1		0.1	l
		6.0	I <sub>O</sub> =20 μA		0.0	0.1		0.1		0.1	V
		4.5	I <sub>O</sub> =4.0 mA		0.17	0.26		0.33		0.40	l
		6.0	I <sub>O</sub> =5.2 mA		0.18	0.26		0.33		0.40	l
I	Input Leakage Current	6.0	V <sub>I</sub> = V <sub>CC</sub> or GND V <sub>I</sub> = 13 V			± 0.1 ± 0.5		± 1 ± 5		± 1	μA
I <sub>CC</sub>	Quiescent Supply Current	6.0	$V_{I} = V_{CC}$ or GND			1		10		20	μΑ

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# **Table 6: AC Electrical Characteristics** ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6 \text{ns}$ )

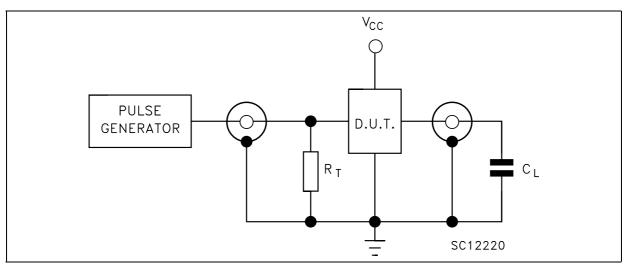
		٦	Test Condition		Test Condition Value									
Symbol	Parameter	v <sub>cc</sub>	Vcc C	V <sub>CC</sub> C <sub>L</sub>		Т	A = 25°	С	-40 to	85°C	-55 to	125°C	Unit	
		(V)	(pF)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.			
t <sub>TLH</sub> t <sub>THL</sub>	Output Transition	2.0				25	60		75		90			
	Time	4.5	50			7	12		15		18	ns		
		6.0				6	10		13		15			
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay	2.0				30	75		95		115			
	Time	4.5	50			9	15		19		23			
		6.0				8	13		16		20	ns		
		2.0				45	100		125		150	115		
		4.5	150			14	20		25		30			
		6.0				12	17		21		26			

#### **Table 7: Capacitive Characteristics**

		Г	Test Condition		Value						
Symbol	Parameter	v <sub>cc</sub>	V <sub>cc</sub>		<sub>A</sub> = 25°	С	-40 to	85°C	-55 to	125°C	Unit
		(V)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
C <sub>IN</sub>	Input Capacitance	5.0			5	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (note 1)	5.0			26						pF

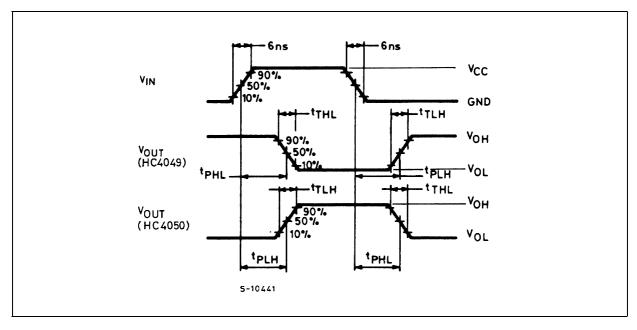
1)  $C_{PD}$  is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation.  $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}/6$  (per gate)

#### Figure 3: Test Circuit



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 $C_L$  = 50pF or equivalent (includes jig and probe capacitance)  $R_T$  =  $Z_{OUT}$  of pulse generator (typically 50 $\Omega$ )

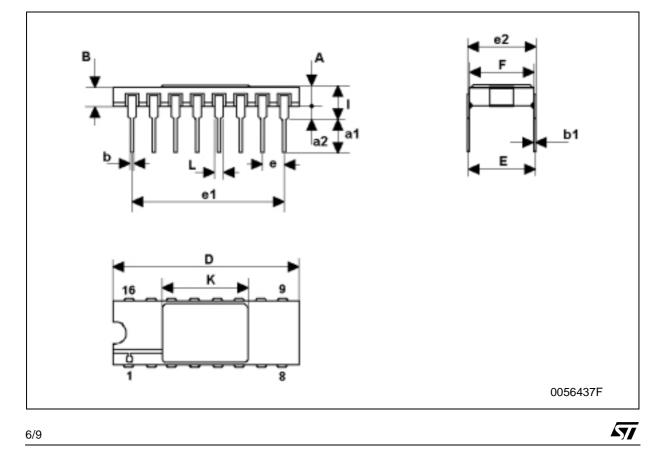






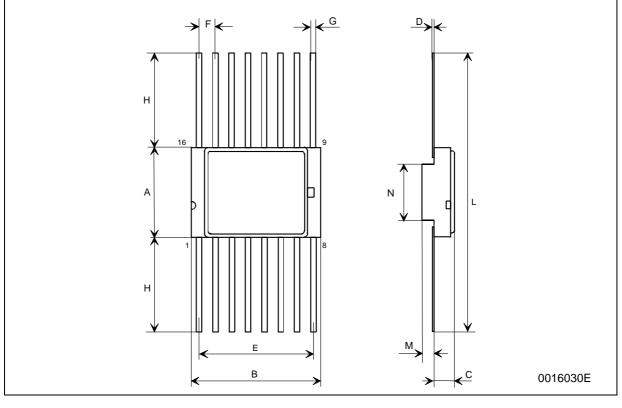
		mm.			inch	
DIM.	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.
А	2.1		2.71	0.083		0.107
a1	3.00		3.70	0.118		0.146
a2	0.63	0.88	1.14	0.025	0.035	0.045
В	1.82		2.39	0.072		0.094
b	0.40	0.45	0.50	0.016	0.018	0.020
b1	0.20	0.254	0.30	0.008	0.010	0.012
D	20.06	20.32	20.58	0.790	0.800	0.810
E	7.36	7.62	7.87	0.290	0.300	0.310
е		2.54			0.100	
e1	17.65	17.78	17.90	0.695	0.700	0.705
e2	7.62	7.87	8.12	0.300	0.310	0.320
F	7.29	7.49	7.70	0.287	0.295	0.303
I			3.83			0.151
К	10.90		12.1	0.429		0.476
L	1.14		1.5	0.045		0.059





DIM.		mm.			inch	
DIW.	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.
А	6.75	6.91	7.06	0.266	0.272	0.278
В	9.76	9.94	10.14	0.384	0.392	0.399
С	1.49		1.95	0.059		0.077
D	0.102	0.127	0.152	0.004	0.005	0.006
Е	8.76	8.89	9.01	0.345	0.350	0.355
F		1.27			0.050	
G	0.38	0.43	0.48	0.015	0.017	0.019
Н	6.0			0.237		
L	18.75		22.0	0.738		0.867
М	0.33	0.38	0.43	0.013	0.015	0.017
Ν		4.31			0.170	





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#### **Table 8: Revision History**

Date	Revision	Description of Changes
14-May-2004	1	First Release

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